



Cookson Electronics

Assembly Materials

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NEWS RELEASE

Release Immediately

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News Release

Release Immediately

**Cookson Electronics Launches ALPHA® JP-500
Pb-free Solder Paste for Use in the MYDATA MY-500 Jet Printer**

South Plainfield, NJ – September 30, 2009 – Cookson Electronics, the leader in soldering materials technology, and MYDATA, the Swedish based producer of the MYDATA MY-500 Jet Printer, announce the release of ALPHA® JP-500 jetting paste. JP-500 is a Pb-free no-clean solder paste developed in co-operation with MYDATA, and is designed for compatibility with this system.

MYDATA's MY-500 Jet Printer is an alternative to screen printing in a high mix production environment that reduces lead times and opens up new design opportunities for the customer. The demand for jet printing has been strong with sales increasing this year by 50% despite generally weak market conditions.

"JP-500 paste allows for rapid line changeover, especially important for high mix customers," says Mitch Holtzer, Global Product Manager for ALPHA solder pastes.

Malin Siberg, the MY-500 Product Manager from MYDATA says, "We have had numerous requests for an ALPHA® solder paste from our customer base. We are pleased that customers now have more choices when selecting solder paste for the MY-500."

ALPHA® JP-500 Solder Paste Specifications:

Designed for use with the MYDATA® MY500 Jet Printer.

Zero Halogen

Wide reflow profile window with good solderability on various board / component finishes.

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- Excellent solder and flux cosmetics after reflow soldering

- Reduction in random solder balling levels, minimizing rework and increasing first time yield
- Excellent pin-test yield for single and double reflow.
- Meets highest IPC 7095 voiding performance classification of Class III.
- Excellent reliability properties, zero halide material
- Capable of high reflow yield without the use of nitrogen

About Cookson Electronics Assembly Materials

Cookson Electronics Assembly Materials, a Cookson Electronics company, is the global leader in the development, manufacturing and sales of innovative materials used in electronic assembly processes. With a unique worldwide presence in 50 locations throughout the Americas, Europe and the Asia/Pacific

region, CEAM supplies a full line of Solder Paste, Stencils, Squeegee Blades, Stencil & PCB Cleaners, Bar Solder, Cored Wire Solder, Wave Soldering

Fluxes, and SMD Adhesives. Cookson Electronics Semiconductor Packaging is the leader in EMC and polymeric materials for semiconductor packaging.

Cookson also offers product technologies for the Photovoltaic market to help lower production costs and increase throughput and yield. Since its founding in 1872, Cookson Electronics has been committed to developing and manufacturing the highest quality soldering materials. That tradition continues today through its innovative products, including its line of environmentally friendly, lead-free electronic assembly products. For more information, visit www.cooksonelectronics.com.

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